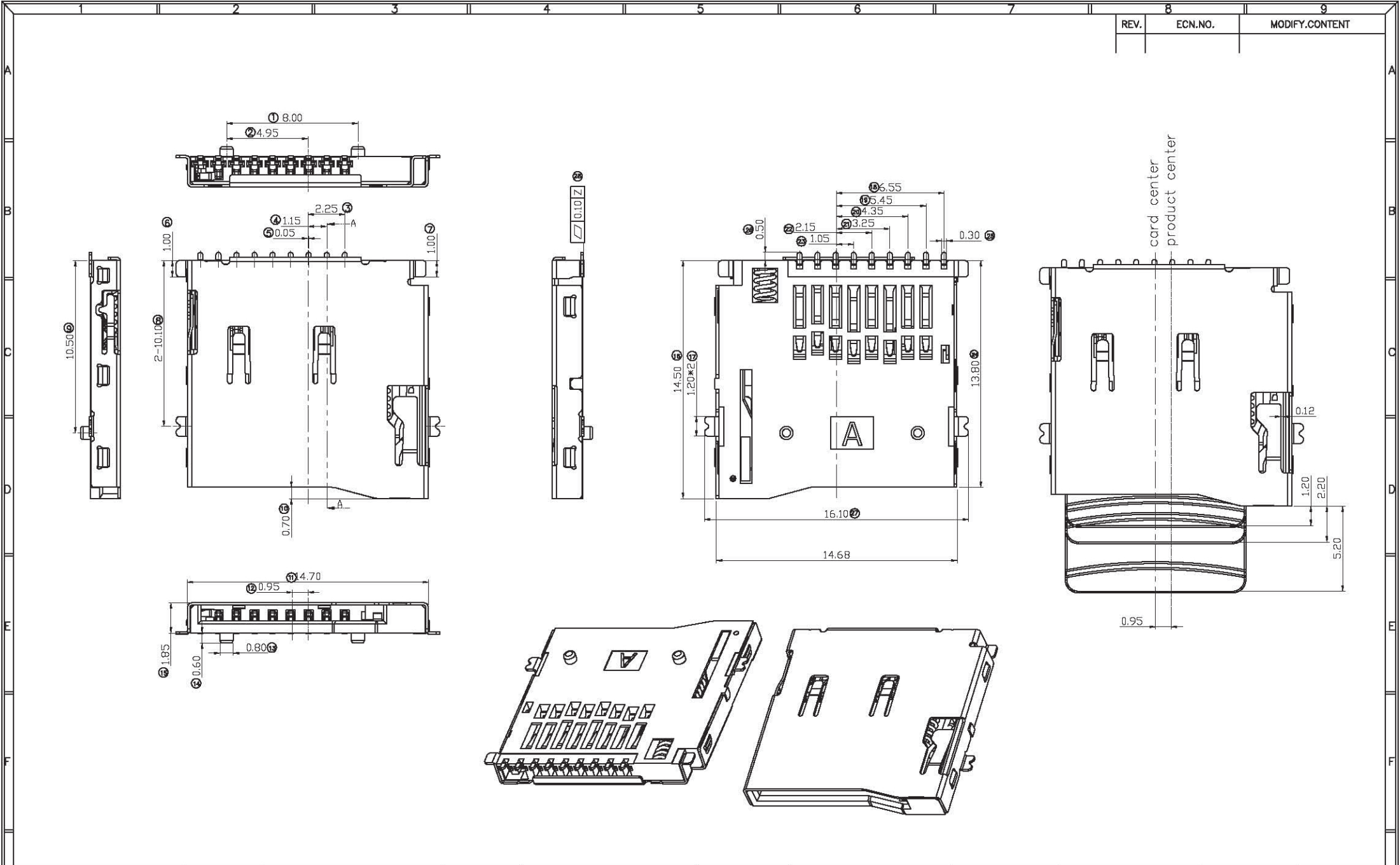
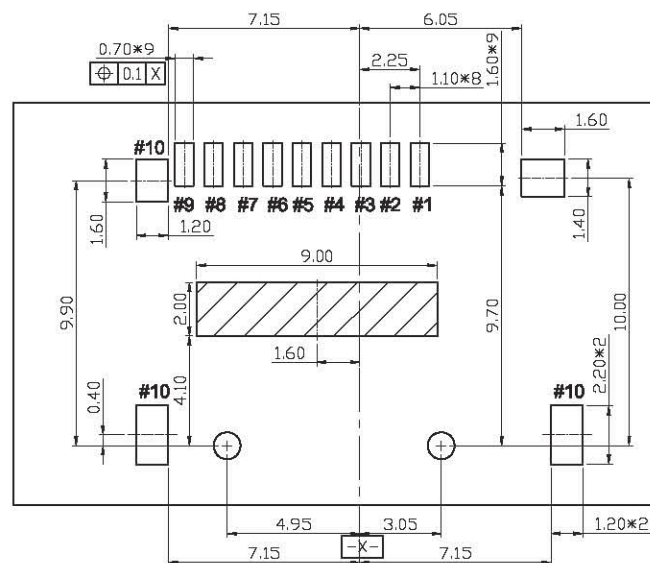


REV.	ECN.NO.	MODIFY.CONTENT

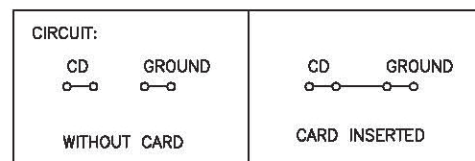


GENERAL TOLERANCE		DWG.NO.	MR02-AP401-00	PART.NO.	MR02-AP4**-**	DRAWN	zgm 2010.11.02	UNIT	mm	SCALE	1:1
x.±0.50	x.*± 5°	REV.	A	TITLE	microsd push conn.(外焊)	CHECKED		东莞市涪程电子科技有限公司			
.x±0.25	.x*± 2°	SIZE									
.xx±0.15	.xx± 1°	A4									
				SHEET	1 OF 2	APPROVED	MIKE 20010. 11. 02				



RECOMMENDED PCB LAYOUT
(ALL TOLERANCE ARE ± 0.05)

 :PROHIBITION AREA



Pin No.		MICRO SD
PIN1	DAT2	1P
PIN2	CD/DAT3	2P
PIN3	CMD	3P
PIN4	VDD	4P
PIN5	CLK	5P
PIN6	VSS	6P
PIN7	DAT0	7P
PIN8	DAT1	8P
PIN9	CARD DETECT	
PIN10	RROUND	

SPECIFICATION

1. Material:

housing: LCP, UL94V-0,color:black.
orbit: PA46, UL94V-0,color:black.
Contacts: Phosphor Bronze,
Tin 160u" at Solder Tail,
Selected Gold on Contact Area Plating.
Shell: Stainless. Pickling

2. Electrical Characteristics:

Operating voltage : 100V AC(rms)/DC.
Current rating : 0.5 A.
Operating Temperature: -25°C~+85°C.
Insulation resistance: 1000M ohms min. at 250VDC
Dielectric withstanding voltage:500 VAC/1minute.
Contact resistance: 100m ohms max.

3. Mechanical characteristics

- 3.1 Mating durability: 10000 cycles.
- 3.2 Insertion force: 2.0Kgf Max.
- 3.3 Extraction force: 0.5Kgf Min.
- 3.4 Mating cycle: 10000 cycles at the speed rate of 400-600 cycles/h; Without distortion of plastic and serious wear and tear in terminal. No signal break.

4. MAJOR DIMENSION: ▼

PART.NO.:
MR02-AP4**-**

01: 胶芯为黑色

- 42: 功能区镀金1U", 锡脚镀雾纯锡至少160U"
43: 功能区镀金3U", 锡脚镀雾纯锡至少180U"
44: 功能区镀金5U", 锡脚镀雾纯锡至少160U"
45: 功能区镀金10U", 锡脚镀雾纯锡至少160U"
46: 功能区镀金15U", 锡脚镀雾纯锡至少160U"
47: 功能区镀金30U", 锡脚镀雾纯锡至少160U"

GENERAL TOLERANCE		DWG.NO.	MR02-AP401-00	PART.NO.	MR02-AP4**-*	DRAWN	zgm 2010.11.02	UNIT	mm	SCALE	1:1
x.±0.50	x.°± 5°	REV.	A	TITLE	mircoasd push conn.(外焊)	CHECKED		东莞市涪程电子科技有限公司			
.x±0.25	.x°± 2°	SIZE		SHEET	2 OF 2	APPROVED	MIKE 20010. 11. 02				
.xx±0.15	.xx°± 1°	A4									